

# TLP291-4

## 1. Applications

- Programmable Logic Controllers (PLCs)
- Switching Power Supplies
- Simplex/Multiplex Data Transmission

## 2. General

The Toshiba TLP291-4 consists of phototransistors optically coupled to gallium arsenide infrared emitting diodes. The TLP291-4 Photocoupler is housed in the very small and thin SO16 package.

Since the TLP291-4 is guaranteed over a wide operating temperature range ( $T_a = -55$  to  $110\text{ }^{\circ}\text{C}$ ), it is suitable for high-density surface mount applications such as programmable controllers.

## 3. Features

- (1) Collector-emitter voltage: 80 V (min)
- (2) Current transfer ratio: 50 % (min)  
GB Rank: 100 % (min)
- (3) Isolation voltage: 2500 Vrms (min)
- (4) Operating temperature:  $-55$  to  $110\text{ }^{\circ}\text{C}$
- (5) Safety standards

UL-approved: UL1577, File No.E67349

cUL-approved: CSA Component Acceptance Service No.5A File No.E67349

VDE-approved: EN60747-5-5 (**Note 1**)

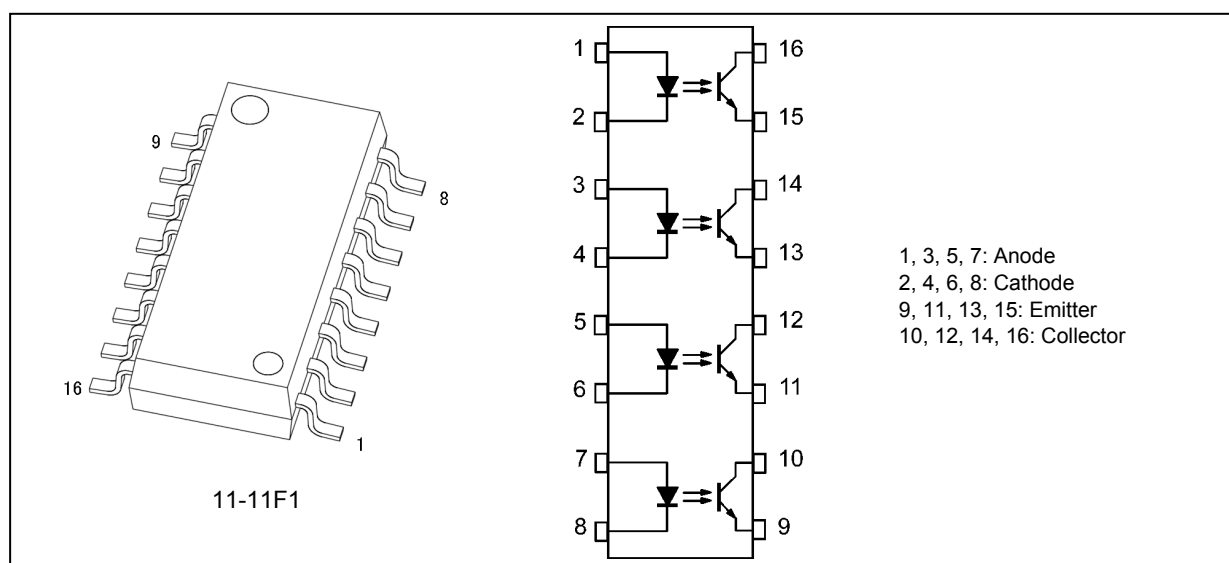
CQC-approved: GB4943.1, GB8898 Thailand Factory



仅适用于海拔 2000m 以下地区安全使用

Note 1: When an EN60747-5-5 approved type is needed, please designate the **Option (V4)**.

## 4. Packaging and Pin Assignment



Start of commercial production

2012-03

## 5. Principle of Operation

### 5.1. Mechanical Parameters

Characteristics	Min	Unit
Creepage distances	5.0	mm
Clearance	5.0	
Internal isolation thickness	0.1	

## 6. Absolute Maximum Ratings (Note) (Unless otherwise specified, $T_a = 25\text{ }^{\circ}\text{C}$ )

	Characteristics	Symbol	Note	Rating	Unit
LED	Input forward current	$I_F$		50	mA
	Input forward current derating ( $T_a \geq 50\text{ }^{\circ}\text{C}$ )	$\Delta I_F / \Delta T_a$		-0.67	mA/ $^{\circ}\text{C}$
	Input forward current (pulsed)	$I_{FP}$		1	A
	Input reverse voltage	$V_R$		5	V
	Input power dissipation	$P_D$		70	mW
	Input power dissipation derating (1 circuit) ( $T_a \geq 50\text{ }^{\circ}\text{C}$ )	$\Delta P_D / \Delta T_a$		-0.93	mW/ $^{\circ}\text{C}$
	Junction temperature	$T_j$		125	$^{\circ}\text{C}$
Detector	Collector-emitter voltage	$V_{CEO}$		80	V
	Emitter-collector voltage	$V_{ECO}$		7	V
	Collector current	$I_C$		50	mA
	Collector power dissipation	$P_C$		100	mW
	Collector power dissipation derating (1 circuit) ( $T_a \geq 25\text{ }^{\circ}\text{C}$ )	$\Delta P_C / \Delta T_a$		-1.0	mW/ $^{\circ}\text{C}$
	Junction temperature	$T_j$		125	$^{\circ}\text{C}$
Common	Operating temperature	$T_{opr}$		-55 to 110	$^{\circ}\text{C}$
	Storage temperature	$T_{stg}$		-55 to 125	$^{\circ}\text{C}$
	Lead soldering temperature (10 s)	$T_{sol}$		260	$^{\circ}\text{C}$
	Total power dissipation	$P_T$		170	mW
	Isolation voltage (AC, 60 s, R.H. $\leq 60\%$ )	$BV_S$	(Note 2)	2500	Vrms

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: Pulse width (PW)  $\leq 100\text{ }\mu\text{s}$ ,  $f = 100\text{ Hz}$

Note 2: This device is considered as a two-terminal device: All pins on the LED side are shorted together, and all pin on the photodetector side are shorted together.

## 7. Electrical Characteristics (Unless otherwise specified, $T_a = 25\text{ }^{\circ}\text{C}$ )

	Characteristics	Symbol	Note	Test Condition	Min	Typ.	Max	Unit
LED	Input forward voltage	$V_F$		$I_F = 10\text{ mA}$	1.1	1.20	1.4	V
	Input reverse current	$I_R$		$V_R = 5\text{ V}$	—	—	10	$\mu\text{A}$
	Input capacitance	$C_t$		$V = 0\text{ V}$ , $f = 1\text{ MHz}$	—	30	—	pF
Detector	Collector-emitter breakdown voltage	$V_{(BR)CEO}$		$I_C = 0.5\text{ mA}$	80	—	—	V
	Emitter-collector breakdown voltage	$V_{(BR)ECO}$		$I_E = 0.1\text{ mA}$	7	—	—	
	Dark Current	$I_{DARK}$		$V_{CE} = 48\text{ V}$	—	0.01	0.1	$\mu\text{A}$
				$V_{CE} = 48\text{ V}$ , $T_a = 85\text{ }^{\circ}\text{C}$	—	2	50	
	Collector-emitter capacitance	$C_{CE}$		$V = 0\text{ V}$ , $f = 1\text{ MHz}$	—	10	—	pF

## 8. Coupled Electrical Characteristics (Unless otherwise specified, $T_a = 25\text{ }^{\circ}\text{C}$ )

Characteristics	Symbol	Note	Test Condition	Min	Typ.	Max	Unit
Current transfer ratio	$I_C/I_F$	(Note 1)	$I_F = 5\text{ mA}$ , $V_{CE} = 5\text{ V}$	50	—	400	%
			$I_F = 5\text{ mA}$ , $V_{CE} = 5\text{ V}$ , Rank GB	100	—	400	
Saturated current transfer ratio	$I_C/I_{F(sat)}$		$I_F = 1\text{ mA}$ , $V_{CE} = 0.4\text{ V}$	—	60	—	
			$I_F = 1\text{ mA}$ , $V_{CE} = 0.4\text{ V}$ , Rank GB	30	—	—	
Collector-emitter saturation voltage	$V_{CE(sat)}$		$I_C = 2.4\text{ mA}$ , $I_F = 8\text{ mA}$	—	—	0.4	V
			$I_C = 0.2\text{ mA}$ , $I_F = 1\text{ mA}$	—	0.2	—	
			$I_C = 0.2\text{ mA}$ , $I_F = 1\text{ mA}$ , Rank GB	—	—	0.4	
OFF-state collector current	$I_{C(off)}$		$V_F = 0.7\text{ V}$ , $V_{CE} = 48\text{ V}$	—	—	10	$\mu\text{A}$

Note 1: See Table 8.1 for current transfer ratio.

**Table 8.1 Current transfer ratio (CTR) Rank (Note) (Unless otherwise specified,  $T_a = 25\text{ }^{\circ}\text{C}$ )**

Rank	Test Condition	Current transfer ratio $I_C/I_F$ Min	Current transfer ratio $I_C/I_F$ Max	Marking of Classification	Unit
Blank	$I_F = 5\text{ mA}$ , $V_{CE} = 5\text{ V}$	50	400	Blank,GB	%
GB		100	400	GB	

Note: Specify both the part number and a rank in this format when ordering.

Example: TLP291-4(GB,E)

For safety standard certification, however, specify the part number alone.

Example: TLP291-4(GB,E: TLP291-4

## 9. Isolation Characteristics (Unless otherwise specified, $T_a = 25\text{ }^{\circ}\text{C}$ )

Characteristics	Symbol	Note	Test Conditions	Min	Typ.	Max	Unit
Total capacitance (input to output)	$C_S$	(Note 1)	$V_S = 0\text{ V}$ , $f = 1\text{ MHz}$	—	0.8	—	pF
Isolation resistance	$R_S$	(Note 1)	$V_S = 500\text{ V}$ , R.H. $\leq 60\%$	$1 \times 10^{12}$	$10^{14}$	—	$\Omega$
Isolation voltage	$BV_S$	(Note 1)	AC, 60 s	2500	—	—	Vrms
			AC, 1 s in oil	—	5000	—	
			DC, 60 s in oil	—	5000	—	Vdc

Note 1: This device is considered as a two-terminal device: All pins on the LED side are shorted together, and all pin on the photodetector side are shorted together.

10. Switching Characteristics (Unless otherwise specified,  $T_a = 25\text{ }^{\circ}\text{C}$ )

Characteristics	Symbol	Note	Test Condition	Min	Typ.	Max	Unit
Rise time	$t_r$		$V_{CC} = 10\text{ V}$ , $I_C = 2\text{ mA}$ , $R_L = 100\text{ }\Omega$	—	2	—	$\mu\text{s}$
Fall time	$t_f$			—	3	—	
Turn-on time	$t_{on}$			—	3	—	
Turn-off time	$t_{off}$			—	3	—	
Turn-on time	$t_{on}$		See Figure 10.1 $R_L = 1.9\text{ k}\Omega$ , $V_{CC} = 5\text{ V}$ , $I_F = 16\text{ mA}$	—	2	—	
Storage time	$t_s$			—	25	—	
Turn-off time	$t_{off}$			—	60	—	

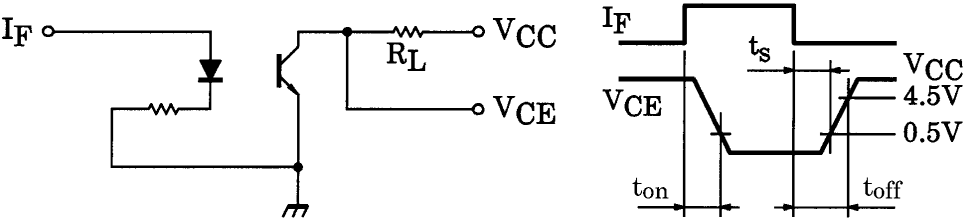


Fig. 10.1 Switching Time Test Circuit and Waveform

11. Characteristics Curves (Note)

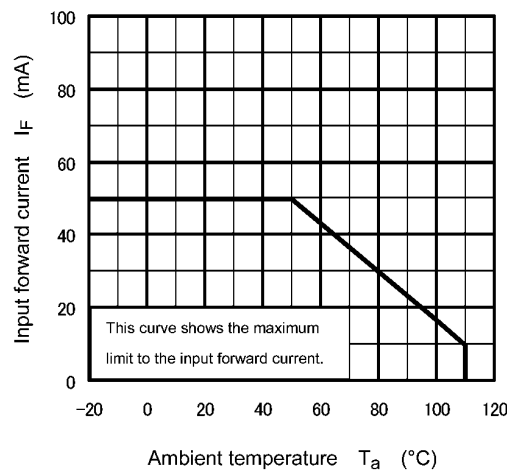


Fig. 11.1  $I_F - T_a$

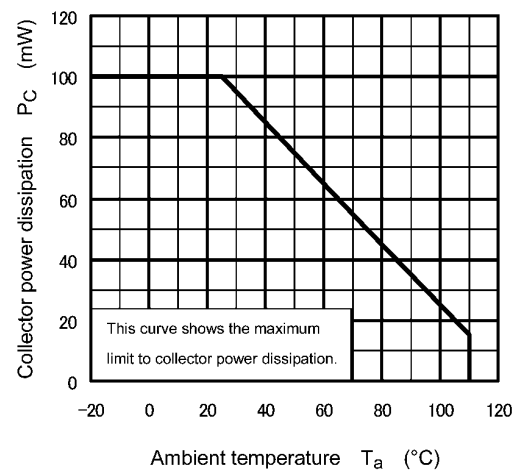


Fig. 11.2  $P_C - T_a$

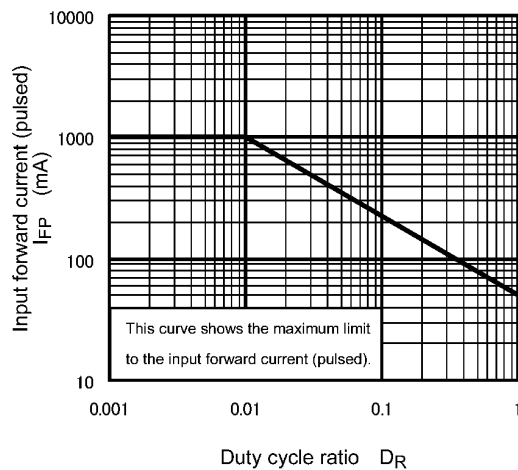


Fig. 11.3  $I_{FP} - D_R$

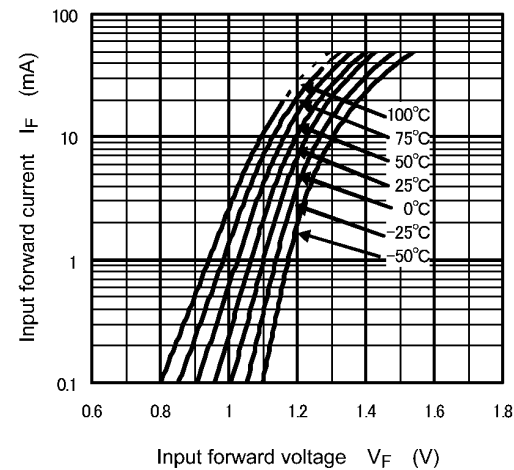


Fig. 11.4  $I_F - V_F$

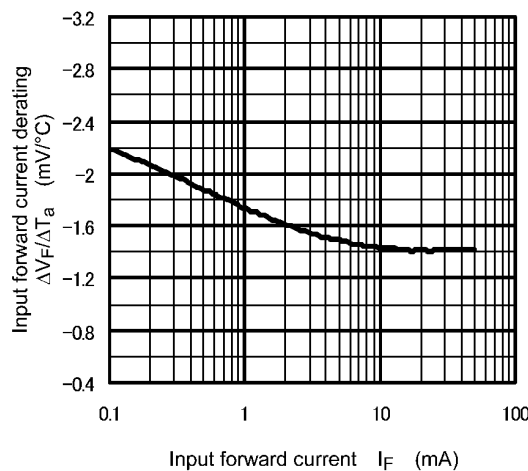


Fig. 11.5  $\Delta V_F/\Delta T_a - I_F$

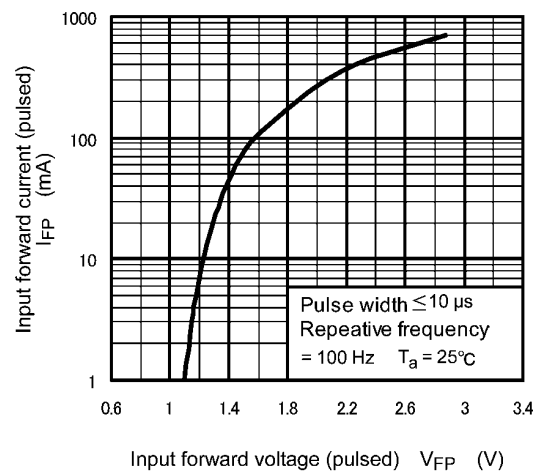


Fig. 11.6  $I_{FP} - V_{FP}$

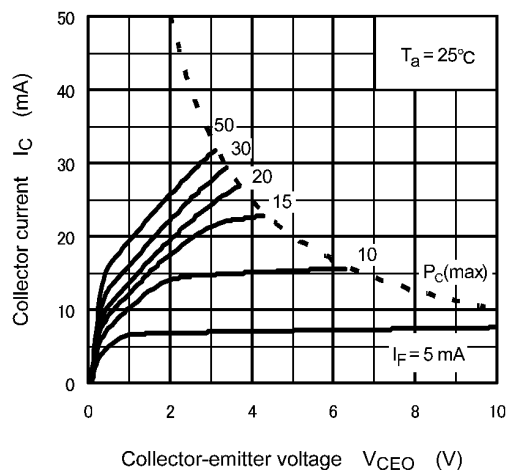


Fig. 11.7  $I_C - V_{CE0}$

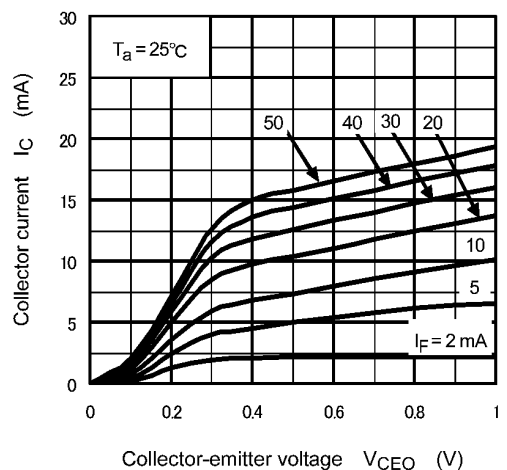


Fig. 11.8  $I_C - V_{CE0}$

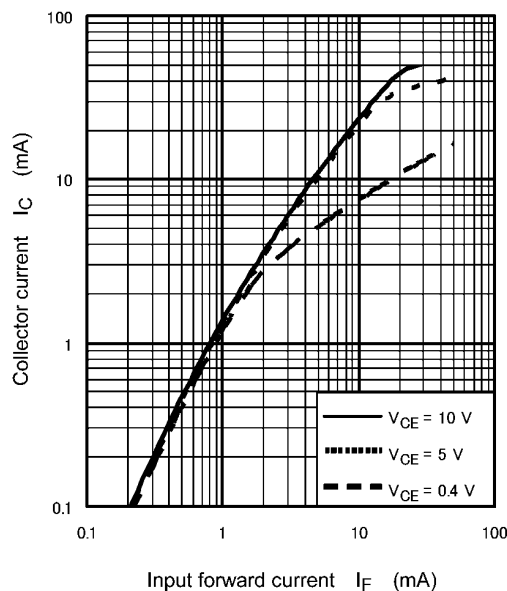


Fig. 11.9  $I_C - I_F$

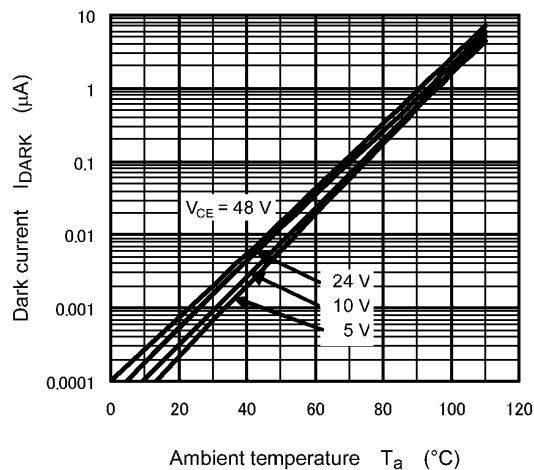


Fig. 11.10  $I_{\text{DARK}} - T_a$

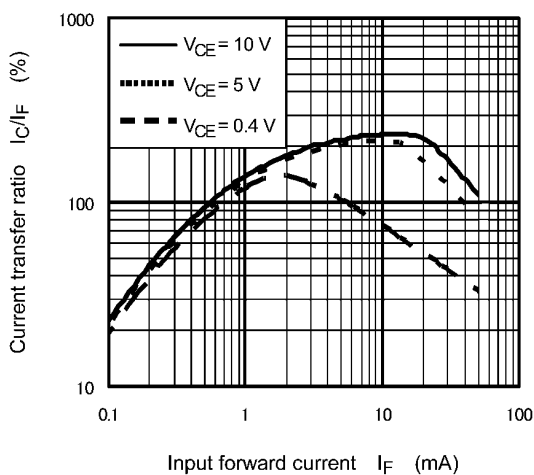


Fig. 11.11  $I_C/I_F - I_F$

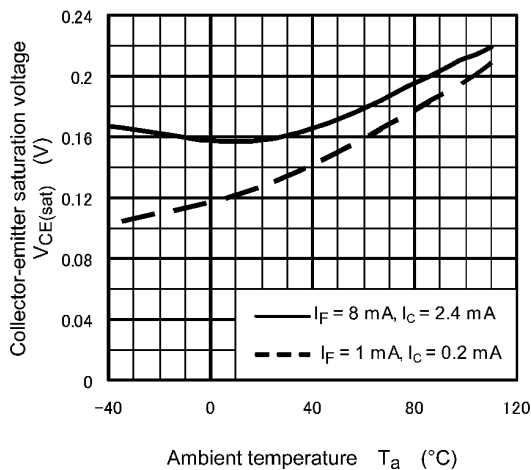


Fig. 11.12  $V_{CE(sat)} - T_a$

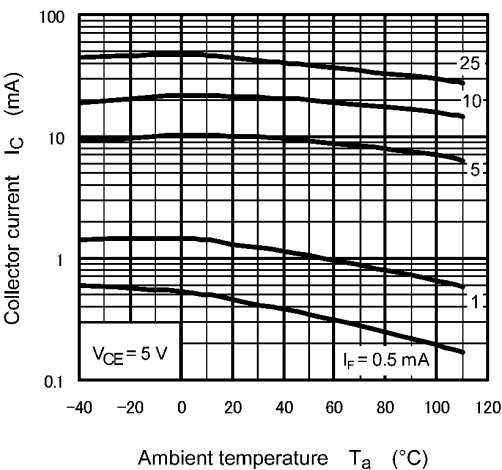


Fig. 11.13  $I_C - T_a$

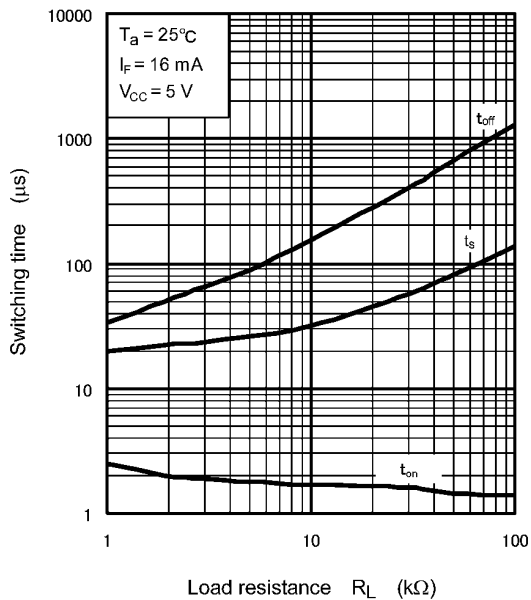


Fig. 11.14 Switching Time -  $R_L$

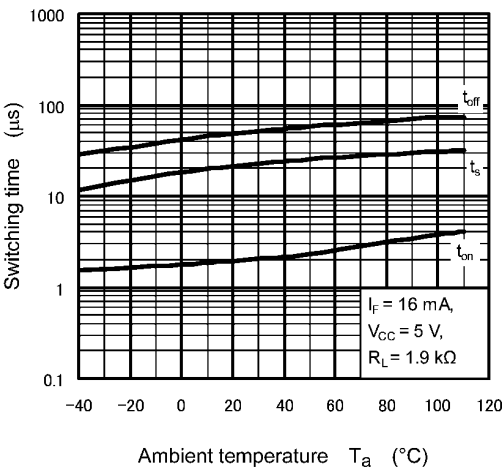


Fig. 11.15 Switching Time -  $T_a$

Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.

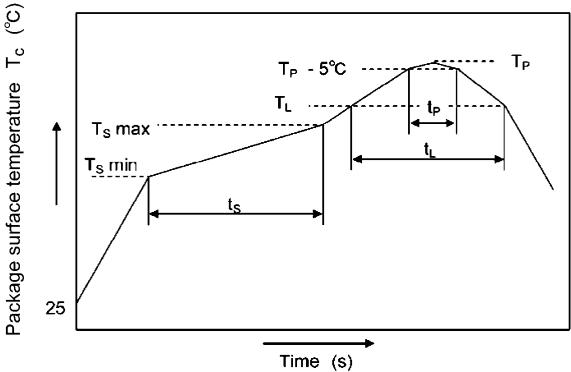
12. Soldering and Storage

12.1. Precautions for Soldering

The soldering temperature should be controlled as closely as possible to the conditions shown below, irrespective of whether a soldering iron or a reflow soldering method is used.

- When using soldering reflow.

The soldering temperature profile is based on the package surface temperature.  
(See the figure shown below, which is based on the package surface temperature.)  
Reflow soldering must be performed once or twice.  
The mounting should be completed with the interval from the first to the last mountings being 2 weeks.



	Symbol	Min	Max	Unit
Preheat temperature	$T_S$	150	200	°C
Preheat time	$t_S$	60	120	s
Ramp-up rate ( $T_L$ to $T_P$ )			3	°C/s
Liquidus temperature	$T_L$	217		°C
Time above $T_L$	$t_L$	60	150	s
Peak temperature	$T_P$		260	°C
Time during which $T_c$ is between ( $T_P - 5$ ) and $T_P$	$t_P$		30	s
Ramp-down rate ( $T_P$ to $T_L$ )			6	°C/s

An Example of a Temperature Profile When Lead(Pb)-Free Solder Is Used

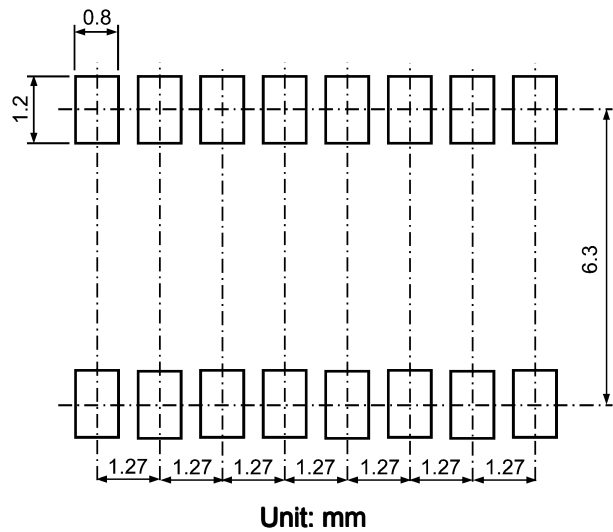
- When using soldering flow  
Preheat the device at a temperature of 150 °C (package surface temperature) for 60 to 120 seconds.  
Mounting condition of 260 °C within 10 seconds is recommended.  
Flow soldering must be performed once.
- When using soldering Iron  
Complete soldering within 10 seconds for lead temperature not exceeding 260 °C or within 3 seconds not exceeding 350 °C  
Heating by soldering iron must be done only once per lead.

12.2. Precautions for General Storage

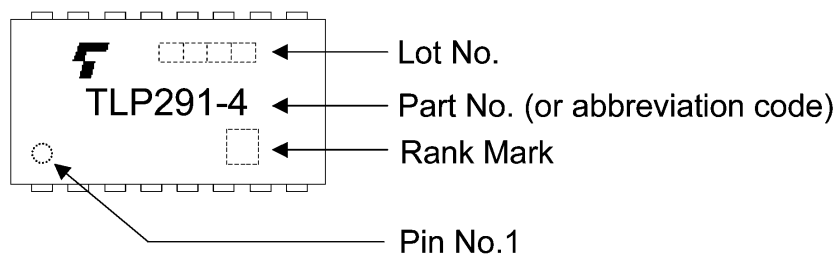
- Avoid storage locations where devices may be exposed to moisture or direct sunlight.
- Follow the precautions printed on the packing label of the device for transportation and storage.
- Keep the storage location temperature and humidity within a range of 5 °C to 35 °C and 45 % to 75 %, respectively.
- Do not store the products in locations with poisonous gases (especially corrosive gases) or in dusty conditions.
- Store the products in locations with minimal temperature fluctuations. Rapid temperature changes during storage can cause condensation, resulting in lead oxidation or corrosion, which will deteriorate the solderability of the leads.
- When restoring devices after removal from their packing, use anti-static containers.
- Do not allow loads to be applied directly to devices while they are in storage.
- If devices have been stored for more than two years under normal storage conditions, it is recommended that you check the leads for ease of soldering prior to use.



13. Land Pattern Dimensions (for reference only)



14. Marking



## 15. Specifications for Embossed-Tape Packing

### 15.1. Applicable Package

Package Name	Product Type
SO16	Mini flat coupler

### 15.2. Product Naming Conventions

Type of package used for shipment is denoted by a symbol suffix after a part number. The method of classification is as below.

Example) TLP291-4(GB-TP,E

Part number: TLP291-4

CTR rank: (GB

Tape type: TP

[[G]]/RoHS COMPATIBLE: E (Note 1)

Note 1: Please contact your Toshiba sales representative for details on environmental information such as the product's RoHS compatibility.

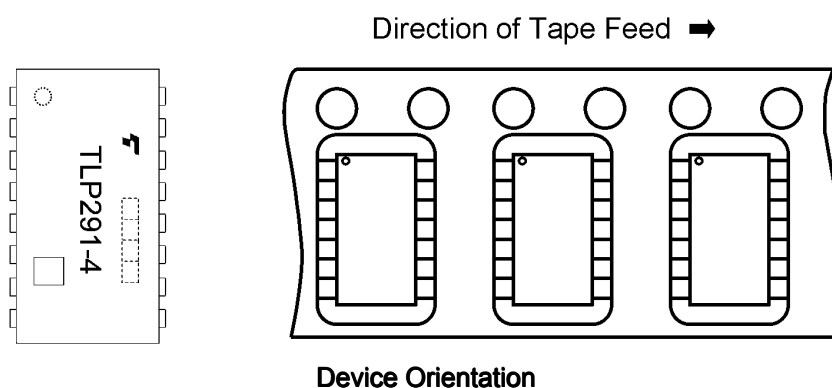
RoHS is the Directive 2011/65/EU of the European Parliament and of the Council of 8 June 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment.

### 15.3. Tape Dimensions Specification

Tape Type	Division	Packing Amount (A unit per reel)
TP	—	2000

#### 15.3.1. Orientation of Device in Relation to Direction of Feed

Device orientation in the carrier cavities as shown in the following figure.



#### 15.3.2. Empty Cavities

Characteristics	Criterion	Remarks
Occurrences of 2 or more successive empty cavities	0 device	Within any given 40-mm section of tape, not including leader and trailer
Single empty cavity	6 devices (max) per reel	Not including leader and trailer

#### 15.3.3. Tape Leader and Trailer

The start end of the tape has 50 or more empty cavities. The hub end of the tape has 50 or more empty cavities and two empty turns only for a cover tape.

15.3.4. Tape Dimensions

Tape material: Plastic (for protection against static electricity)

Unit: mm

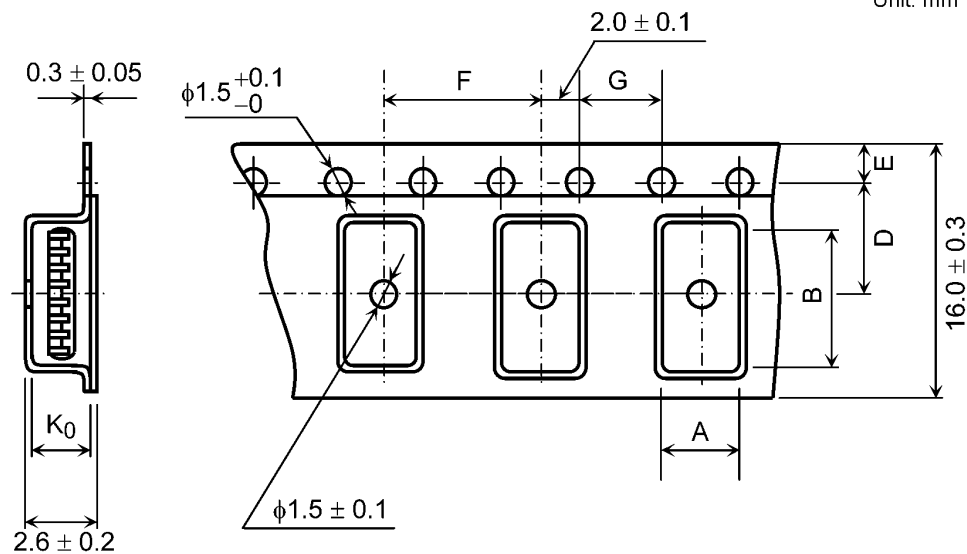


Table Tape Dimensions (unit: mm, tolerance: ±0.1)

Symbol	Dimension	Remark
A	7.5	—
B	10.5	—
D	7.5	Center line of embossed cavity and sprocket hole
E	1.75	Distance between tape edge and sprocket hole center
F	12.0	Cumulative error +0.1/-0.3 (max) per 10 empty cavities holes
G	4.0	Cumulative error +0.1/-0.3 (max) per 10 sprocket holes
K <sub>0</sub>	2.2	Internal space

15.3.5. Reel Specification

Material: Plastic (for protection against static electricity)

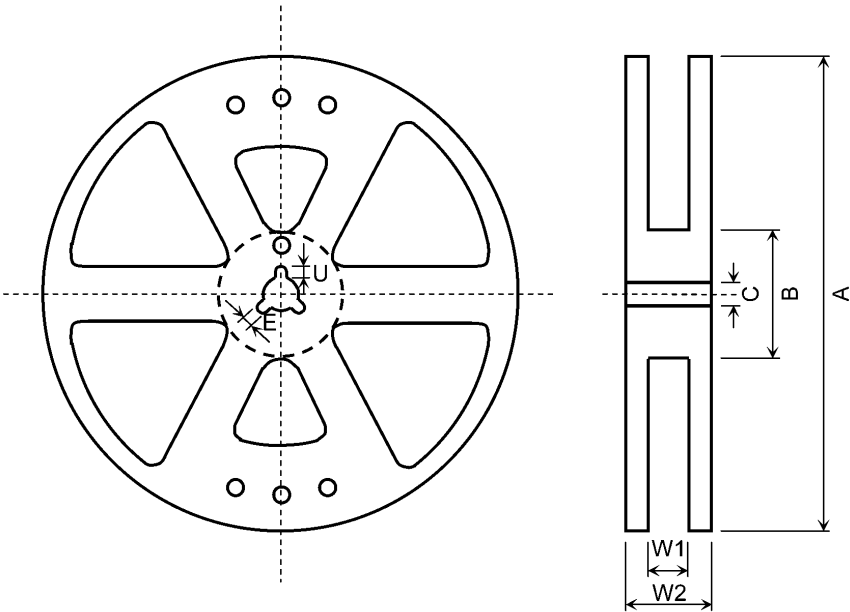
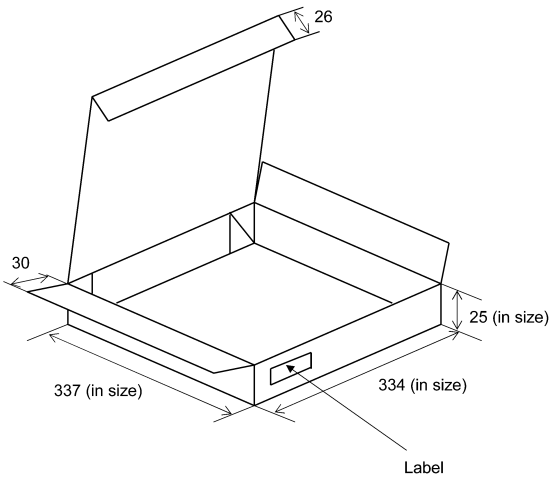


Table Reel Dimensions (unit: mm)

Symbol	Dimension
A	$\phi 330 \pm 2$
B	$\phi 80 \pm 1$ or $\phi 100 \pm 1$
C	$\phi 13 \pm 0.5$
E	$2.0 \pm 0.5$
U	$4.0 \pm 0.5$
W1	$17.5 \pm 0.5$
W2	$21.5 \pm 1.0$

15.4. Packing (Note)



1 reel/carton (unit: mm)

Note: Taping reel diameter:  $\phi 330$  mm

15.5. Label Format

- (1) Carton: The label provides the part number, quantity, lot number, the Toshiba logo, etc.
- (2) Reel: The label provides the part number, the taping name, quantity, lot number, etc.

## 15.6. Ordering Information

When placing an order, please specify the part number, CTR rank, tape type and quantity as shown in the following example.

Example) TLP291-4(GB-TP,E 2000 pcs

Part number: TLP291-4

CTR rank: (GB

Tape type: TP

[[G]]/RoHS COMPATIBLE: E (**Note 1**)

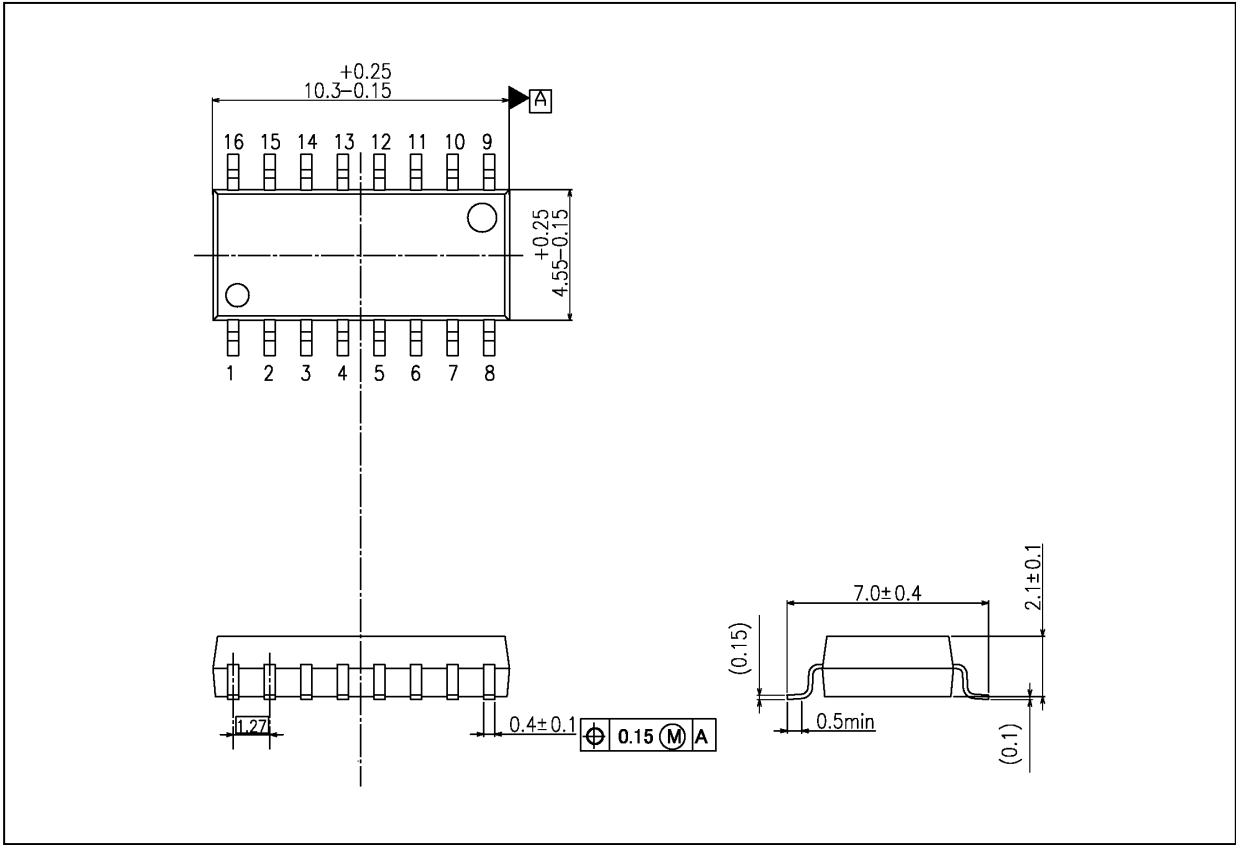
Quantity (must be a multiple of 2000): 2000 pcs

Note 1: Please contact your Toshiba sales representative for details on environmental information such as the product's RoHS compatibility.

RoHS is the Directive 2011/65/EU of the European Parliament and of the Council of 8 June 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment.

Package Dimensions

Unit: mm



Weight: 0.19 g (typ.)

Package Name(s)
TOSHIBA: 11-11F1

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